# Product End-of-Life Disassembly Instructions

| Product Category: Networking Equipment |
|---|
| **Marketing Name / Model [List multiple models if applicable.]** |
| HP 7510 Switch Chassis(JD238C) |
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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

| Item Description | Notes | Quantity of items included in product |
|---|---|---|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 2 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 0 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 0 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 0 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | 0 |
| External electrical cables and cords | | 0 |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | 0 |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos | | 0 |

| | | |
|---|---|---|
| Components, parts and materials containing refractory ceramic fibers | | 0 |
| Components, parts and materials containing radioactive substances | | 0 |

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|---|---|
| Screw driver | 2# |
| | |
| | |
| | |
| | |

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

3.1.1 Guidance of treatments to the product:

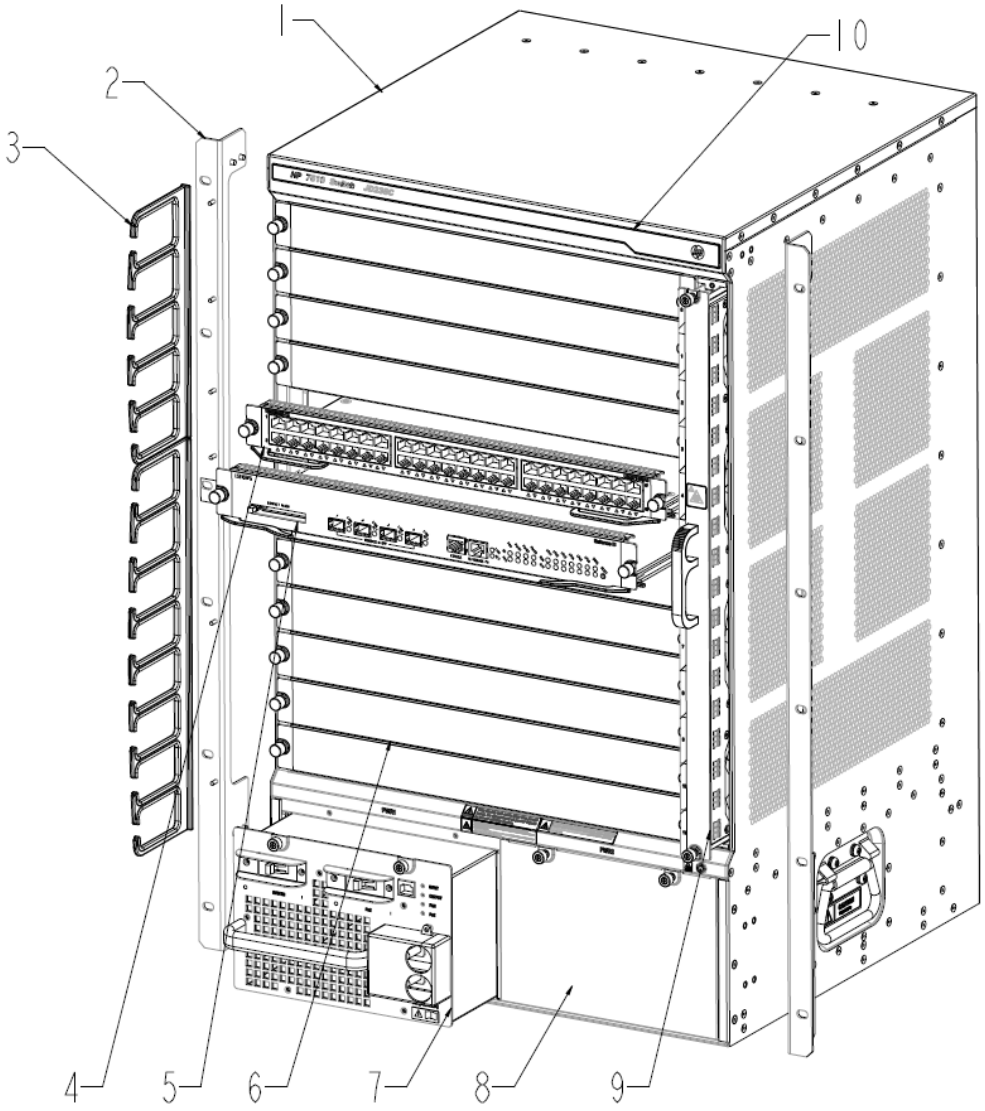


Figure 1 Front of HP 75010

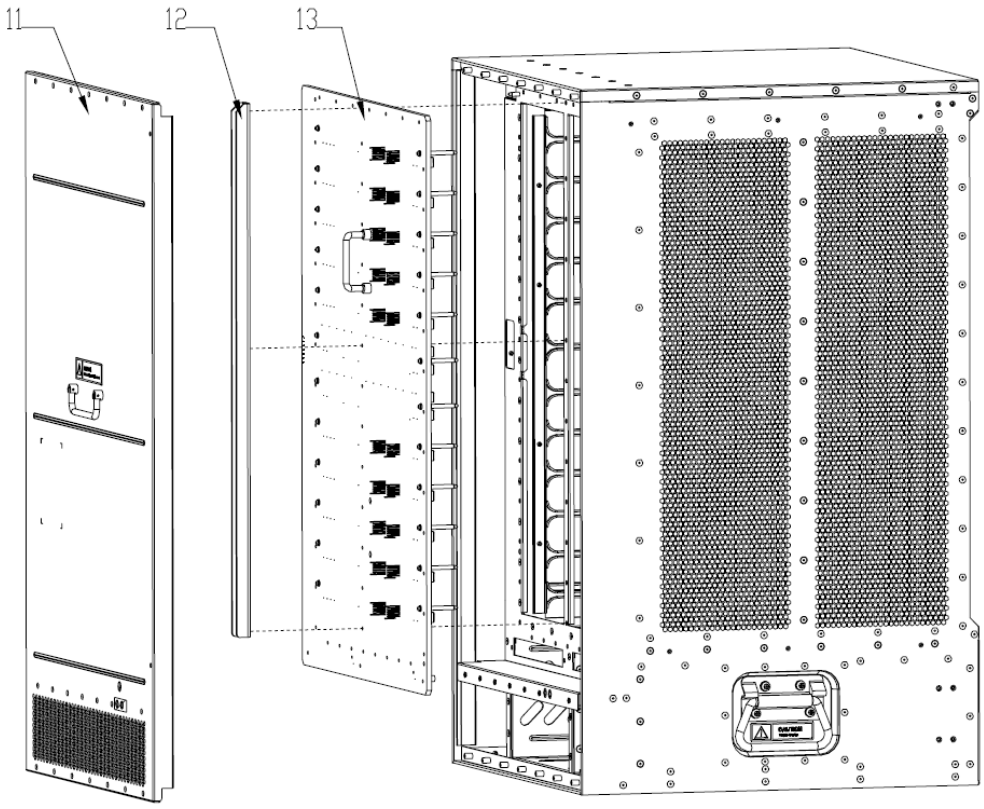


Figure 2 Rear of HP 75010

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2;
2. Unscrew the screws on cabling rack 3, and then remove cabling rack 3 from mounting angle 2;
3. Unscrew the screws on front panel 4, and then remove front panel 4;
4. Unscrew the screws on front panel 5, and then remove front panel 5;
5. Unscrew the screws on filler panel 6, and then remove filler panel 6. The others should be removed in the same way;
6. Unscrew the screws on power supply module 7, and then remove power supply module 7;
7. Unscrew the screws on filler panel 8, and then remove filler panel 8;
8. Unscrew the screws on fan module frame 9, and then remove fan module frame 9;
9. Remove film 10;
10. Unscrew the screws on rear cover plate 11, and then remove rear cover plate 11;
11. Unscrew the screws on reinforcing plate 12, and then remove reinforcing plate 12;
12. Unscrew the screws on PCB 13, and then remove PCB 13;
13. Remove all of the labels;
14. Remove all of shielding fingers.

3.1.2 Guidance of treatments to module 4:

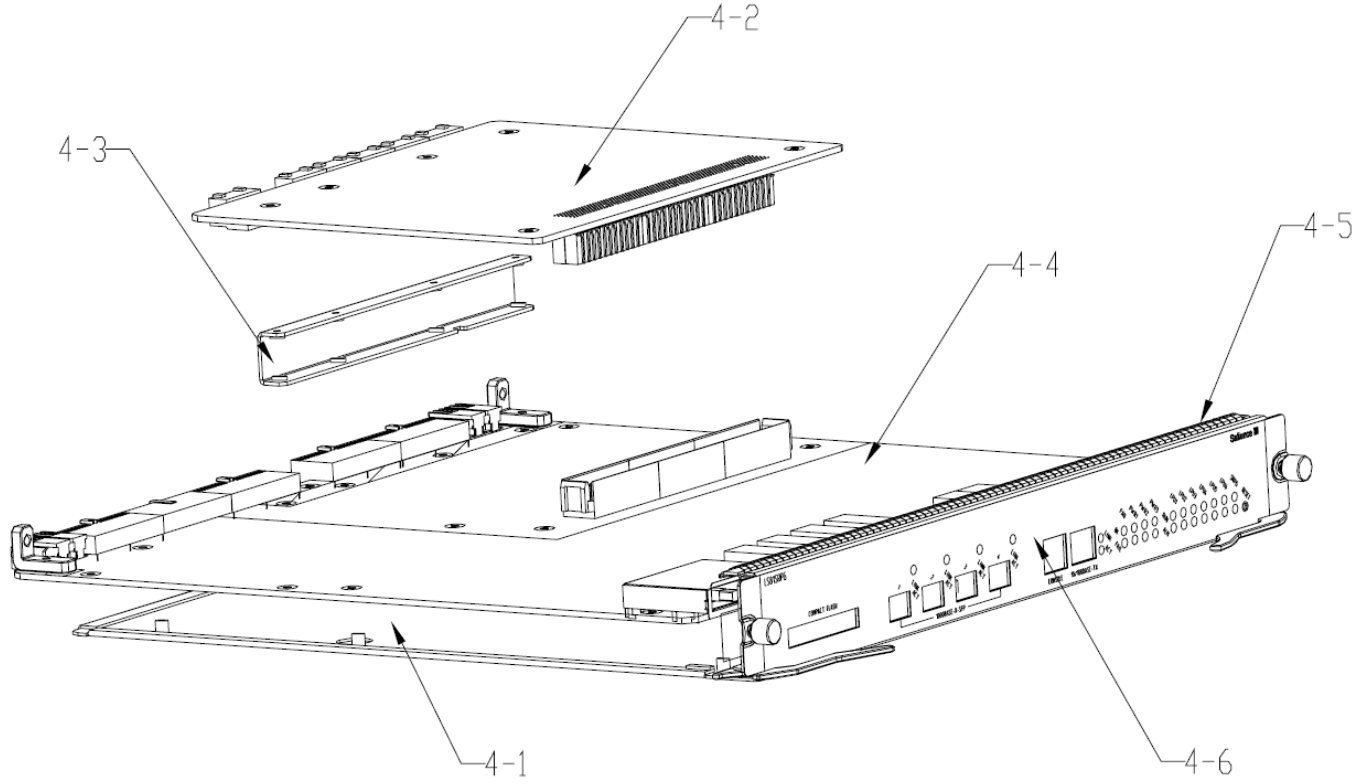


Figure 3 Treatments to module 4

1. Unscrew the screws on PCB 4-2, and then remove PCB 4-2;
2. Unscrew the screws on PCB support plate 4-3, and then remove PCB support plate 4-3;
3. Unscrew the screws on PCB 4-4, and then remove PCB 4-4;
4. Remove shielding finger 4-5 from front panel 4-1;
5. Remove film 4-6 from front panel 4-1.

3.1.3 Guidance of treatments to module 5:

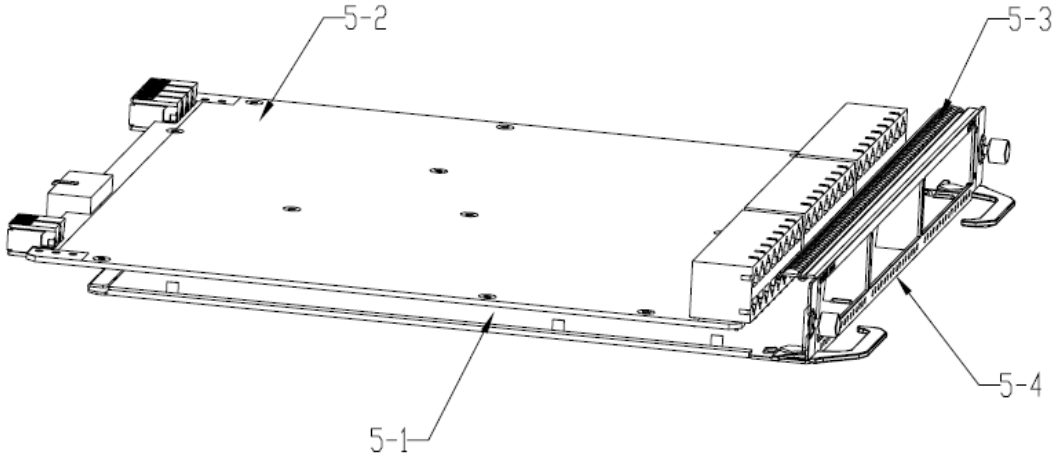


Figure 4 Treatments to module 5

1. Unscrew the screws on PCB 5-2, and then remove PCB 5-2;
2. Remove shielding finger 5-3 from front panel 5-1;
3. Remove film 5-4 from front panel 5-1;

3.1.4 Guidance of treatments to blank panel 6:

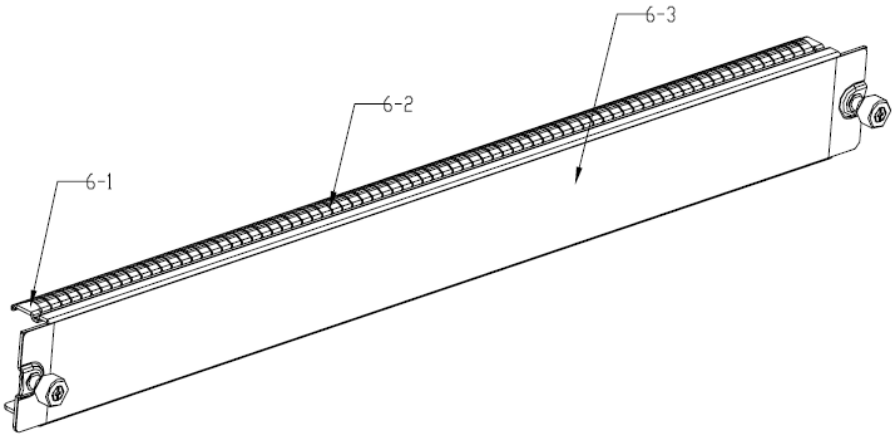


Figure 5 Treatments to blank panel 6

1. Remove shielding finger 6-2 from blank panel 6-1;
2. Remove film 6-3 from blank panel 6-1;

3.1.7 Guidance of treatments to fan module frame 9

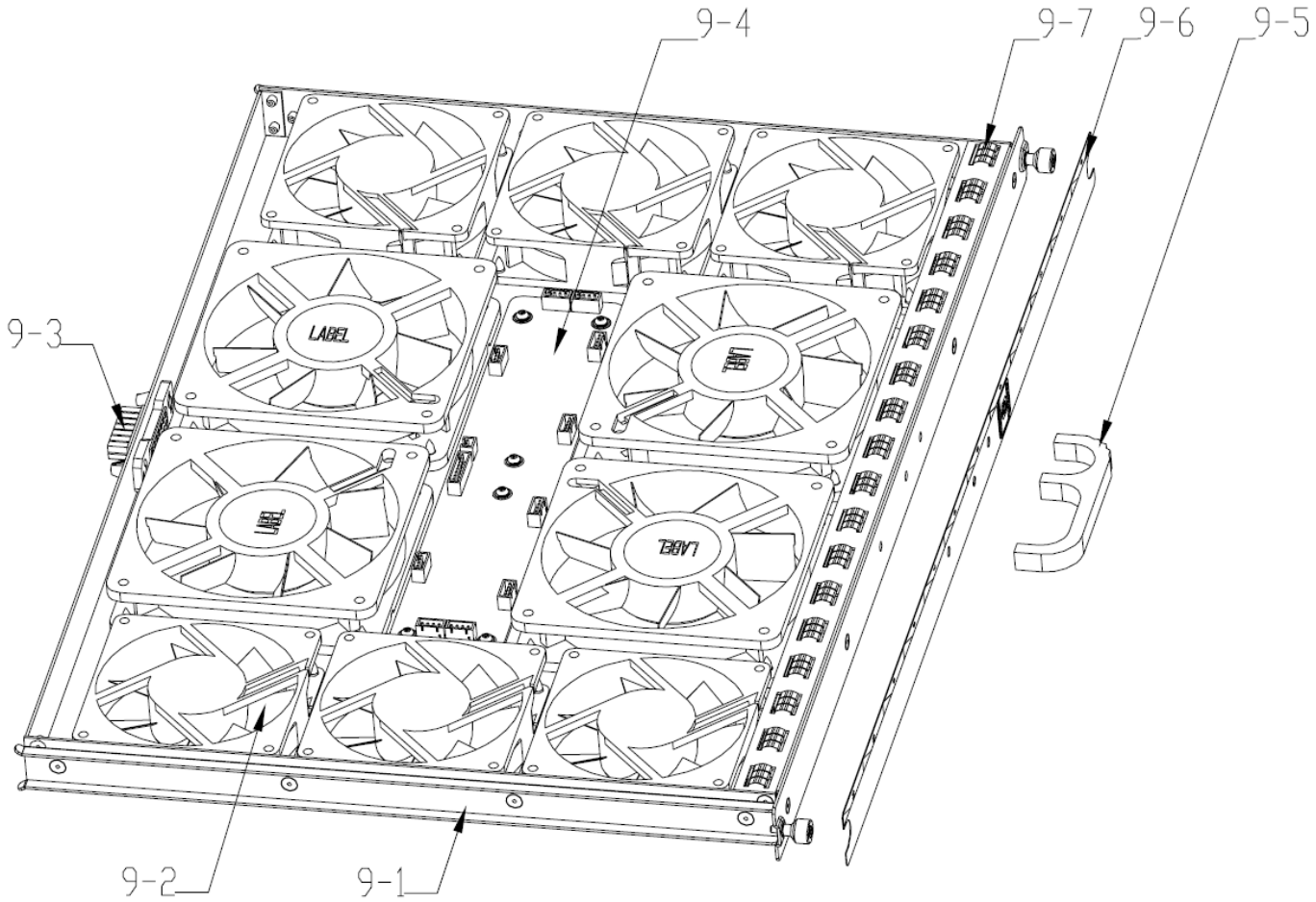


Figure 6 Treatments to fan module frame 9

1. Remove the ten fans 9-2 from fan frame 9-1;;
2. Remove plug 9-3 from fan frame 9-1;
3. Unscrew the screws on PCB 9-4, and then remove PCB 9-4;
4. Remove all of the inner cables;
5. Unscrew the screws on handle 9-5, and then remove handle 9-5;
6. Remove film 9-6 from fan frame 9-1;
7. Remove shielding finger 9-7 from fan frame 9-1;

3.2 Material of the facility built

| Facility | Components | Material | Weight(g) | Weight percentage | Selective treatment for materials and components | Details |
|---|---|---|---|---|---|---|
| 1 | | Fe | 24967 | 46.02% | | Fe recycling |
| 2 | | Fe | 1340 | 2.47% | | Fe recycling |
| 3 | | ABS | 95 | 0.18% | | |
| 4 | | | | | | |
| | 4-1 | Fe | 1566 | 2.89% | | Fe recycling |
| | 4-2 | Complex PWB | 528 | 0.97% | The surface of PCB is greater than 10 square centimeters | |
| | 4-3 | Fe | 93 | 0.17% | | Fe recycling |
| | 4-4 | Complex PWB | 1000 | 1.84% | The surface of PCB is greater than 10 square centimeters | |
| 5 | | | | | | |
| | 5-1 | Fe | 1487 | 2.74% | | Fe recycling |
| | 5-2 | Complex PWB | 1000 | 1.84% | The surface of PCB is greater than 10 square centimeters | |
| 6 | | | | | | |
| | 6-1 | Fe | 303*10 | 5.59% | | Fe recycling |
| 7 | | Complex PWB+Fe | 8021 | 14.79% | 1. Containing brominated flame retardants ;<br>2. The surface of PCB is greater than 10 square centimeters;<br>3. Electrolyte capacitor height | Fe recycling |
| 8 | | Fe | 524 | 0.97% | | Fe recycling |
| 9 | | | | | | |
| | 9-1 | Fe | 1362 | 2.51% | | Fe recycling |
| | 9-2 | Pla | 183*4+98*6 | 2.43% | | Pla recycling |
| | 9-4 | Complex PWB | 97 | 0.18% | The surface of PCB is greater than 10 square centimeters | |
| 11 | | Fe | 3469 | 6.39% | | Fe recycling |
| 12 | | Fe | 425 | 0.78% | | Fe recycling |
| 13 | | Complex PWB | 3000 | 5.53% | The surface of PCB is greater than 10 square centimeters | |
| cables | 04043396<br>0404A05T<br>04042967<br>0404A07K | Cu, Pla | 925 | 1.71% | 1. Containing brominated flame retardants<br>2. 04043396 is external cables | Cu、Pla recycling |

4. Revised record

| Date | Version | Author | Modify content |
|---|---|---|---|
| 2015.06.26 | V0 | Xu Jianbin | Initial version |
| | | | |